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Date: March 19, 2019

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A DESIGN PERSPECTIVE

SECOND EDITION

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To Kathelijn, Karthiyayani, Krithivasan,
and our Parents

"Qu'est-ce que l'homme dans la nature?
Un néant a l'égard de l'infini,
un tout al l'égard du néant,
un milieu entre rien et tout."

"What is man in nature?
Nothing in relation to the infinite,
everything in relation to nothing,
a mean between nothing and everything."

Blaise Pascal, *Pensées*, n. 4, 1670.

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